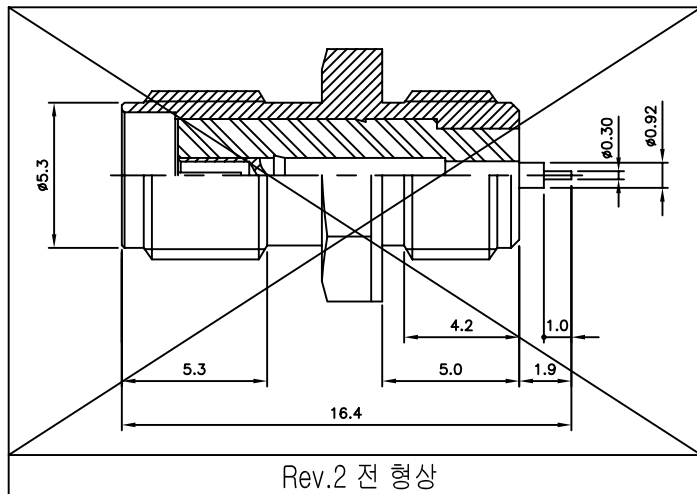
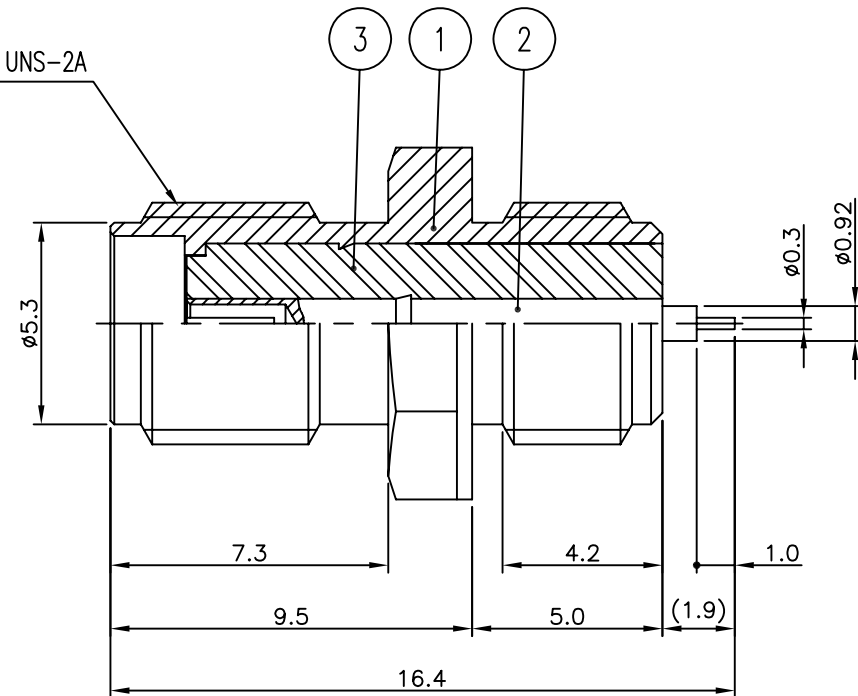
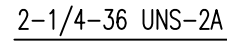
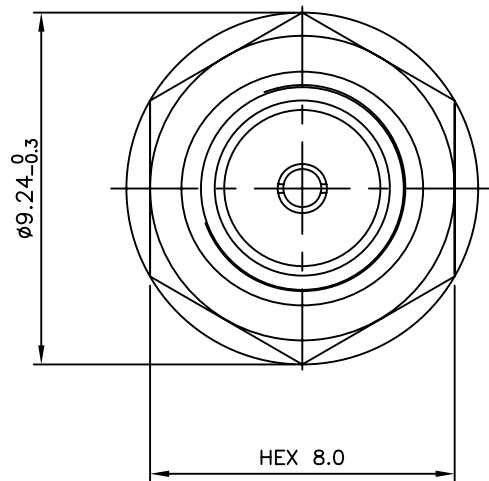


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1R	Initial Registration			2009.07.28.
1	[설변처리No.201704-0003] 조립성 개선 바디 및 님 뉴시턱 구조 변경	I.C.KIM		2017.04.11.
2	바디 공용화로 인한 부품 코드 변경	S.Y.EUN	I.C.KIM	2019.10.07.



	3	INSULATOR	1	TEFLON		DIN02877-N/1 DIN01822-N/2 DIN01822-N/1
	2	CONTACT	1	BeCu C17300	Gold Plate	DCT02057-5/3 DCT02057-5/2 DCT02057-5/1
	1	BODY	1	MBsBD C3604BD-F	Nickel Plate	DBD00318-5/4 DBD02554-5/2 DBD02554-5/1
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017				
	±0.1	2019. 10. 07.							
	Angle	APPROVED BY	I.C.KIM						
MATERIAL	±1°	CHECKED BY	TITLE			SMA50 SOLDER END JB (F/F)			
	_____	DRAWN BY							S.Y.EUN
FINISH	_____	SCALE	UNIT		A4	DWG NO.		CN02436-7/1	
		5/1	mm			REVISION	2	SHEET	1 of 1